

Title (en)
METAL COMPOSITION CONTAINING METAL ACETILIDE, BLANK HAVING METALLIC COATING FORMED THEREWITH, AND METHOD FOR FORMING THE METALLIC COATING

Title (de)
METALLZUSAMMENSETZUNG MIT ACETYLID, DAMIT METALLISCH BESCHICHTETER ROHLING UND VERFAHREN ZUR BESCHICHTUNG

Title (fr)
COMPOSITION METALLIQUE CONTENANT DE L'ACETYLURE DE METAL, EBAUCHE DOTEE D'UN REVETEMENT METALLIQUE FORME A L'AIDE DE LADITE COMPOSITION ET PROCEDE DE FORMATION DUDIT REVETEMENT METALLIQUE

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Application
EP 98953055 A 19981113

Priority
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• JP 36380397 A 19971126

Abstract (en)
[origin: EP0976848A1] A metallic composition such as a metal liquid, metal paste, etc. is manufactured by using a metal acetylide compound expressed by the general formula $M(-C \text{ IDENTICAL } C-R)_n$ (in the formula, M indicates a metal atom, n indicates the valence number of the metal atom M, and R is a hydrocarbon group which may or may not contain oxygen atoms) as an organo-metal source, and by mixing and kneading an organic solvent and/or a resin together with such a metal acetylide compound. When this metallic composition is applied in a desired pattern to prescribed portions of electronic elements or ornamental items such as porcelain vessels or glass, etc., and at least these prescribed portions are dried and heated, the result is that the organic substances other than the metal are broken down and released, and the metal alone is sintered in the pattern. This pattern shows an ornamental metallic luster in the case of ornamental items, and forms electrodes in the case of electronic elements. Since the metal acetylide compounds do not contain sulfur or halogen elements, these compounds do not release environmental contaminants such as sulfurous acid gas, halogen gases, etc. even when fired; accordingly, such compounds can contribute to the cleaning of the environment. Furthermore, since these compounds have a high solubility in organic solvents, they are suitable as raw materials in metallic compositions. Moreover, the metallic film that is formed after firing is smooth and finely textured and has a high metallic luster and electrical conductivity; accordingly, this film can form high-quality ornamental films in ornamental items and electrodes in electronic component, etc.

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Citation (search report)
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